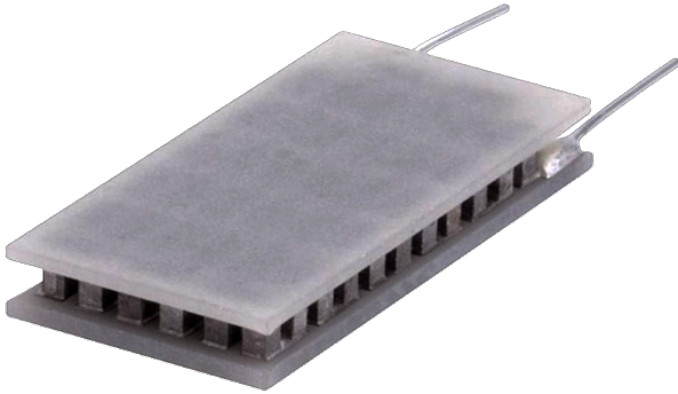


HiTemp ET Series Thermoelectric Cooler

Note: This product is not recommended for new designs.
 This product series has been replaced with the HiTemp ETX Series.
 The recommended replacement is:
 MFG Part Number: 387006901
 Description: OTX19-35-F1N-0612-21-EP-W2.25

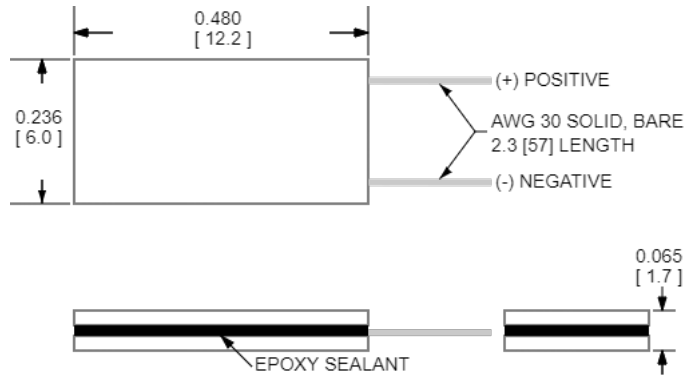


Features

- High-temperature operation
- Reliable solid-state
- No sound or vibration
- Environmentally-friendly
- RoHS-compliant

Applications

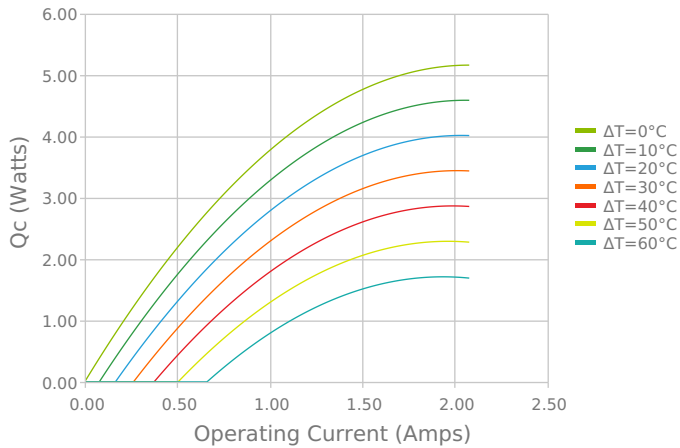
- Peltier Cooling for Refrigerated Centrifuges
- Peltier Cooling for Machine Vision
- Thermoelectric Cooling for CMOS Sensors
- Cooling Solutions for Autonomous Systems
- Peltier Cooling for Digital
- Light Processors



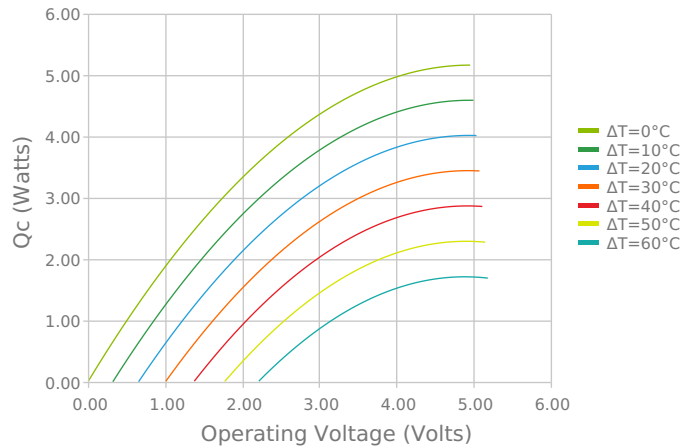
CERAMIC MATERIAL: AlN
 SOLDER CONSTRUCTION: 232°C, SbSn
 INCHES [MM]
 Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

ELECTRICAL AND THERMAL PERFORMANCE

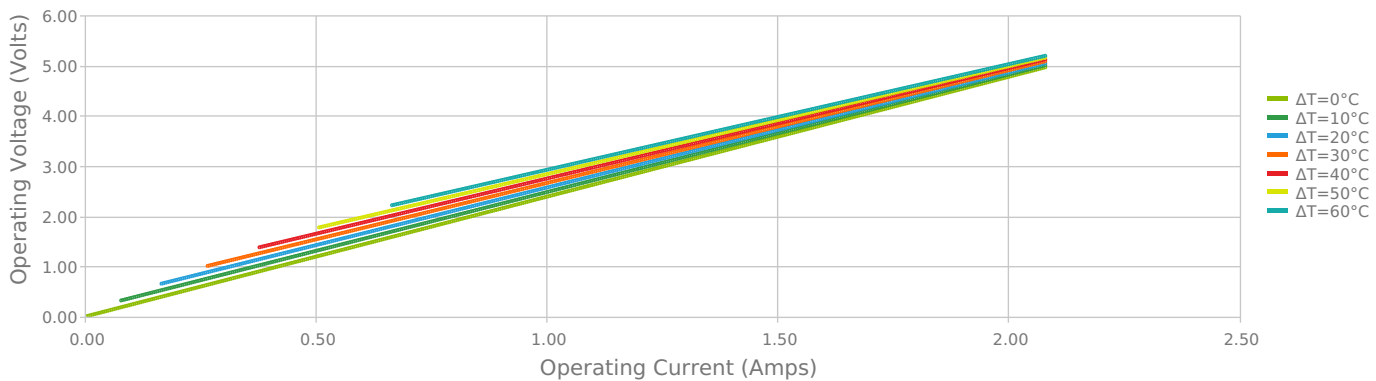
Heat Pumped at Cold Side
 Thot = 85 °C



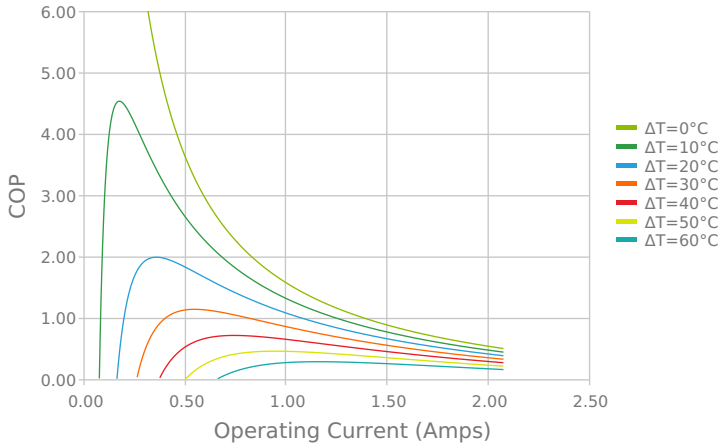
Heat Pumped at Cold Side
 Thot = 85 °C



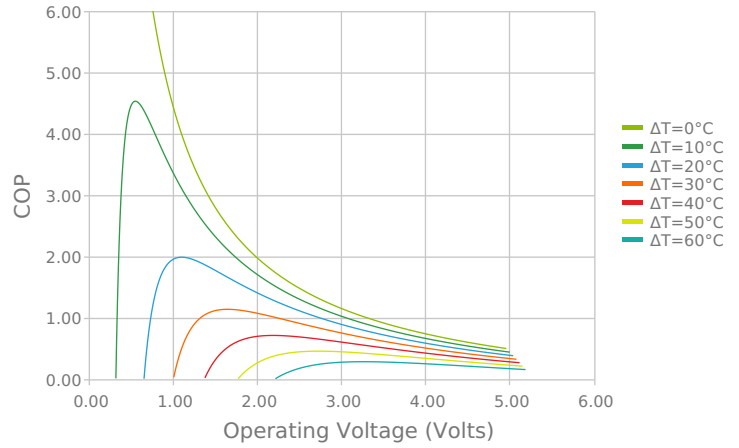
Current vs Voltage (I vs V)
 Thot = 85 °C



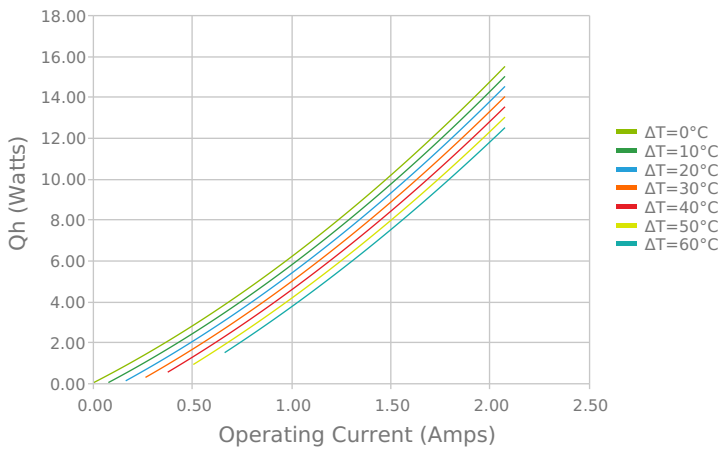
Coefficient of Performance (COP = Qc/Pin)
Thot = 85 °C



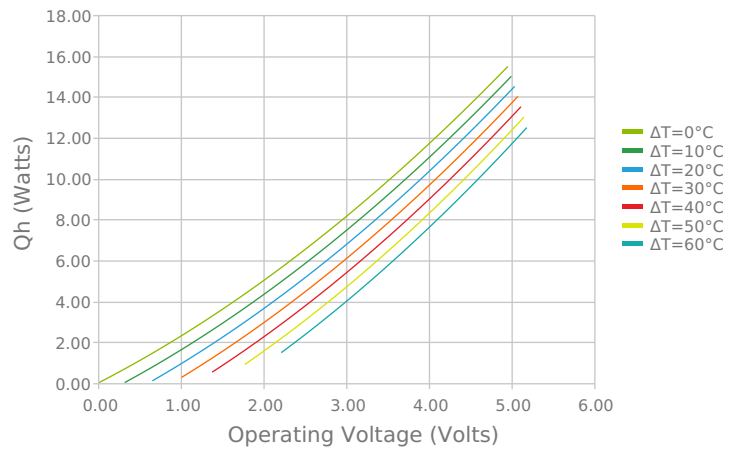
Coefficient of Performance (COP = Qc/Pin)
Thot = 85 °C



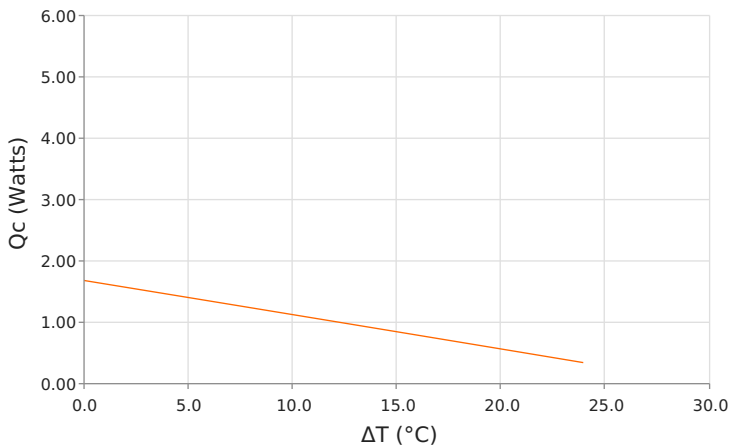
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
Thot = 85 °C



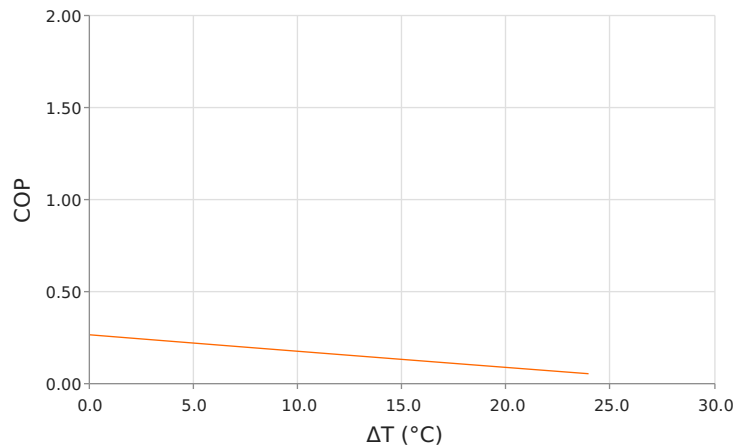
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
Thot = 85 °C



Heat Pumped at Cold Side (Qc)
Thot = 85 °C | Current = 1.6 Amps



Coefficient of Performance (COP = Qc/Pin)
Thot = 85 °C | Current = 1.6 Amps



SPECIFICATIONS*

Hot Side Temperature	50.0 °C	85.0 °C	110.0 °C
Qcmax ($\Delta T = 0$)	4.7 Watts	5.2 Watts	5.4 Watts
ΔT_{max} ($Q_c = 0$)	77.9°C	89.3°C	96.2°C
I_{max} (I @ ΔT_{max})	1.9 Amps	1.8 Amps	1.8 Amps
V_{max} (V @ ΔT_{max})	4.2 Volts	4.8 Volts	5.3 Volts
Module Resistance	2.05 Ohms	2.39 Ohms	2.61 Ohms
Max Operating Temperature	150 °C		
Weight	1.0 gram(s)		

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
11	1.651 ±0.051 mm 0.065 ± 0.0020 in	0.051 mm / 0.051 mm 0.002 in / 0.002 in	Lapped	Lapped	50.8 mm 2.00 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

1. Max operating temperature: 150°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation

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Date: 01/08/2022